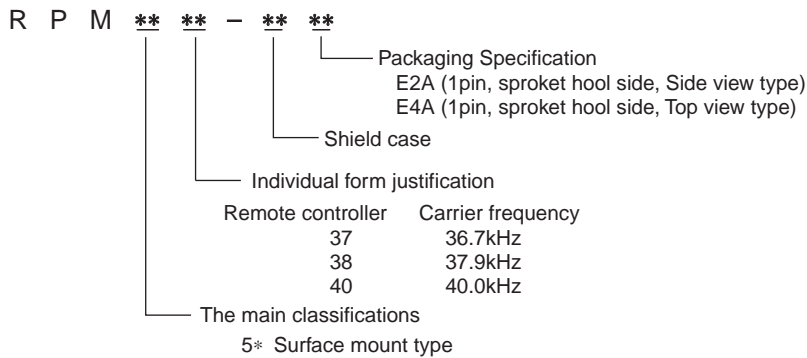
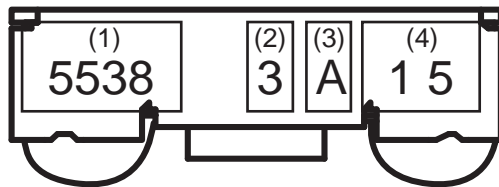


### ● Product Designation



### ● Marking



(1) Model name

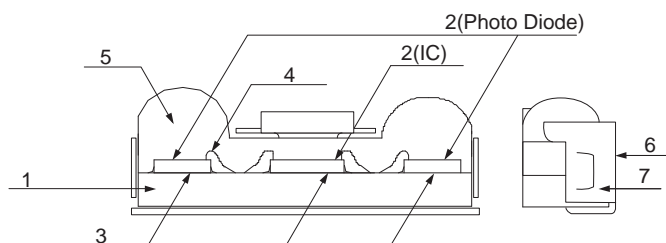
(2) Lot number : The ends of a manufacture year (A.D.)

(3) Lot number : The manufacture month

Month	Jan.	Feb.	Mar.	Apr.	May	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Mark	1	2	3	4	5	6	7	8	9	A	B	C

(4) Manufacture lot number

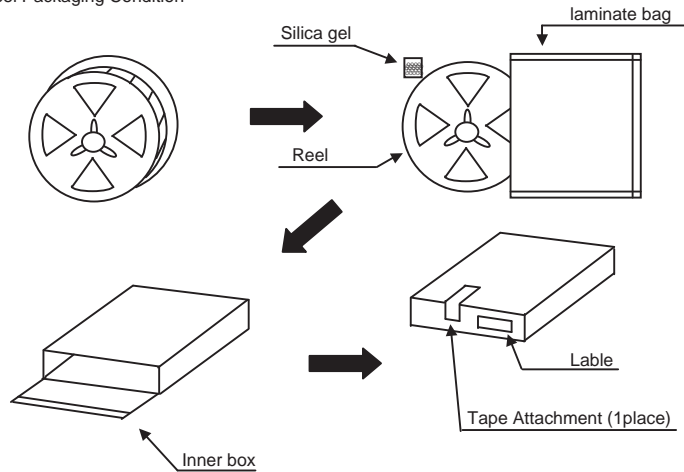
### ● Internal structure figure



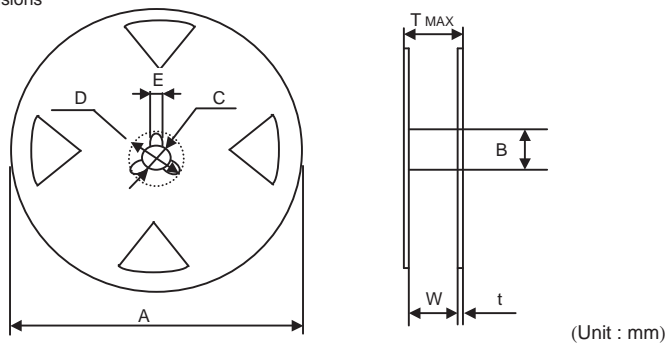
No.	Part Name	Materials (method)
1.	Frame	Glass epoxy (Outer lead : Au plated)
2.	Die	IC / Silicone Photo Diode / Silicone
3.	Die Attach	Insulating Paste
4.	Wire	Au Wire (Thermosonic wire-bonding)
5.	Molding	Non-fireproof Epoxy Resin (Transfer Mold)
6.	Marking	laser Marking
7.	Shield case	Fe (Sn plated)

Packing specification

1. Reel Packaging Condition



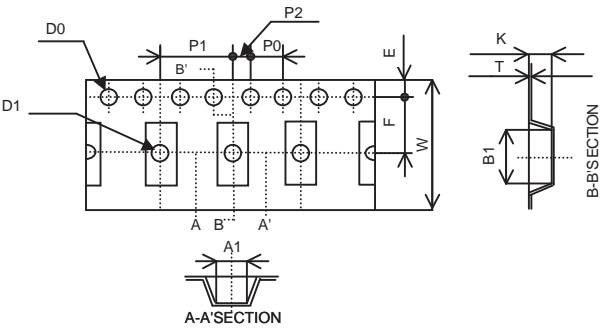
2. Reel Dimensions



Real size / Tape size	A	B	C	D	E	W	t	T MAX
16	330±2	φ100±1	13.0±0.2	21.0±0.8	2.0±0.5	17.4±1	2.0±1	22.4

Packaging Style	Part No.	Side / Top View	Taping Type No.	Quantity per unit (PCS)	Basic ordering unit (PCS)
Embossed taping	RPM5537-H14	SIDE VIEW	E2A	2500	2500
	RPM5538-H14				
	RPM5540-H14				
	RPM5337-H14				
	RPM5338-H14				
	RPM5340-H14				
	RPM5537-H12	TOP VIEW	E4A		
	RPM5538-H12				
	RPM5540-H12				
	RPM5337-H12				
	RPM5338-H12				
	RPM5340-H12				
	RPMS2371-H19				
	RPMS2381-H19				
	RPMS2401-H19				
	RPMS1371-H19				
	RPMS1381-H19				
	RPMS1401-H19				

3. Tape Dimension



Tape code No.	Package	A1	B1	D0	D1	E	F	P0	P1	P2	T	K	W
E2A	RSLP7A-H14	3.30	8.40	φ1.5	φ1.6	1.75	7.50	4.00	8.00	2.00	0.30	2.50	16.00
E4A	RSLP7A-H12	3.40	8.20	φ1.5	φ1.6	1.75	7.50	4.00	8.00	2.00	0.30	2.83	16.00

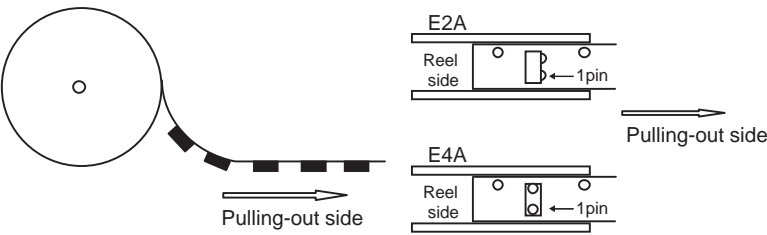
(Unit : mm)

<Tape Material>                      Holes = PS                      Cover Tape = PE

4. Products Direction in the taping pocket

E2A··· Every Module's lans fase to pulling-out side the taping.

E4A··· Every Module's lans fase to top of the taping pocket.

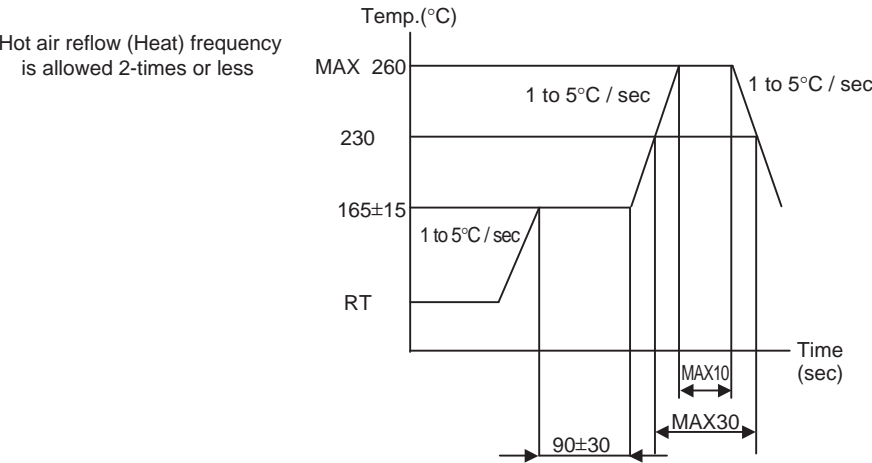


● Recommended soldering conditions

[Recommended mounting conditions]

Hot air reflow condition

Package surface temperature (°C)



Condition of partial heat method (by soldering iron) is used ;  
350°C MAX 3sec MAX / pin

### ● Recommended Conditions for Flux and Cleaning

- (1) Flux  
Rosin flux with less chlorine. (Chlorine not more than 0.2wt%)
- (2) Conditions for Ultrasonic cleaning
 

Frequency	: 28KHz
Ultrasonic wave output	: MAX 15W / liter
Solvent	: Alcoholic solvent is recommended. (From the viewpoint of respecting a decision in protecting the ozone layer, our company dose not recommend cleaning with freon or chloride solvents.)
Time	: Within 30sec (Within 3min when ultrasonic wave is not used)
Solution temperature	: MAX 40°C

#### <Cautions>

- A device must not resonate.
- The device print board must not contact directly to the vibration source.
- Do not rub the marked area of the package with a brush or fingers during cleaning and when the cleaning solvent is adhered to the device.
- From the viewpoint of respecting a decision in protecting the ozone layer, out company does not recommend cleaning with fleon or chloride solvents(1.1.1-Trichlorotane), However, both quality and reliability of the product will not suffer as long as the recommended conditions for cleaning are maintained and controlled.

### ● Baking process

Condition	Temp.	Baking time	Total bake time
In reel(tape)	60 to 65°C	≥ 48 hours	≤ 100 hours
In bulk	125°C	≥24 hours	≤ 50 hours

The above will be applied :

- 1) When the packing is left opened for more than 72 hours.
- 2) When product is kept unused (in unopened packing) over 12 months.

#### (1) <Baking condition's for Taping storage>

<Baking condition of the reel after 72hours opening the moisuture proof packing>

- Minimum baking time is 48hours at 60 to 65°C.
- Total baking time must not exceed 100hours in total.
- Only bake 2 times maximum.

#### (2) <Baking Condition's for Bulk storage>

<Baking condition of the reel after 72hours opening the moisuture proof packing>

- Minimum baking time is 24hours at 125°C.
- Total baking time must not exceed 50hours in total.
- Only bake 2 times maximum.

**Solder-dip method mounting is not recommended because it gives extra stress on the device, which will lead to bad influence on its reliability.**

## Notes

- 1) The information contained herein is subject to change without notice.
- 2) Before you use our Products, please contact our sales representative and verify the latest specifications :
- 3) Although ROHM is continuously working to improve product reliability and quality, semiconductors can break down and malfunction due to various factors.  
Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Products beyond the rating specified by ROHM.
- 4) Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The peripheral conditions must be taken into account when designing circuits for mass production.
- 5) The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly, any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use of such technical information.
- 6) The Products are intended for use in general electronic equipment (i.e. AV/OA devices, communication, consumer systems, gaming/entertainment sets) as well as the applications indicated in this document.
- 7) The Products specified in this document are not designed to be radiation tolerant.
- 8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
- 9) Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
- 10) ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.
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